



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 5067
Mizuki NAGAI et al. : Attorney Docket No. 2003_1338
Serial No. 10/664,078 : Group Art Unit 1753
Filed September 17, 2003 : Examiner Edna Wong
COPPER-PLATING LIQUID, PLATING
METHOD AND PLATING APPARATUS : Mail Stop: AF

RESPONSE TO FINAL REJECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Final Rejection dated August 16, 2005, the period for response having been extended for one month by the attached petition, please amend the present application as follows:

OKing to enter. (M) 12/27/05